



Update Notification

Document # : FPCN20386XB1

Issue Date: 6 April 2016

Title of Change:	Reliability data Update to FPCN20386XB - Qualification of ON Semiconductor Vietnam (OSV) for the Assembly and Test of the listed SCR products in DPAK package.				
Proposed first ship date:	23 May 2016 or earlier upon customers approval				
Contact information:	Contact your local ON Semiconductor Sales Office or <Gk.Sua@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office or <Dong.Ta@onsemi.com>				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Cheanching.Sim@onsemi.com>				
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.				
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☒ Test Change ☐ Other _____				
Change Sub-Category(s): ☒ Manufacturing Site Change/Addition ☐ Material Change ☐ Datasheet/Product Doc change ☐ Manufacturing Process Change ☐ Product specific change ☐ Shipping/Packaging/Marking ☐ Other: _____					
Sites Affected: ☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ON Dong Nai Province, Vietnam ON Seremban, Malaysia ☐ External Foundry/Subcon site(s)					
Description and Purpose: This Update Notification is issued to customers to provide updated modification Reliability data of HTRB and HTFB test from the qualification vehicle of MCR12DSNT4G. FPCN 20386XB was issued on 15th Feb, 2016 to include additional SCR devices. This FPCN announces the planned capacity expansion of ON Semiconductor's assembly and test operations of DPAK discrete packaged products, currently built at ON Semiconductor Seremban, Malaysia facility to ON Semiconductor Vietnam (OSV). Upon the expiration of this FPCN, SCR devices may be processed at either location. These products have been qualified to commodity/commercial requirements. These products will continue being Pb-free, Halide free and RoHS compliant.					
Reliability Data Summary: QV DEVICE NAME: MCR12DSNT4G PACKAGE: DPAK					
Test	Specification	Condition	Interval	Sample size	Results
HTRB	JESD22-A108	Ta= 100°C, Tj(est) =110C, 80% max rated V	1008 hrs	84 pcs/3 lots	0/252
HTFB	JESD22-A108	Ta= 100°C, Tj(est) =110C, 80% max rated V	1008 hrs	84 pcs/3 lots	0/252
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	84 pcs/3 lots	0/252
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta= +25°C, delta Tj= 100°C On/off = 2min	15000 cyc	84 pcs/3 lots	0/252
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	84 pcs/3 lots	0/252
H3TRB	JESD22-A101	85°C, 85% RH, 18.8psig, bias	1008 hrs	84 pcs/3 lots	0/252
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	96 hrs	84 pcs/3 lots	0/252
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		336 pcs/3 lots	0/1008
RSH	JESD22- B106	Ta= 265°C, 10 sec		30 pcs/3 lots	0/90
SD	JSTD002	Ta= 245°C, 10 sec		15 pcs/3 lots	0/45

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
MCR12DCMT4G	MCR12DSNT4G
MCR8DCNT4G	MCR12DSNT4G
MCR8DSNT4G	MCR12DSNT4G